

Lot-to-lot variability of BN grades for space electric propulsion applications

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1. NASA Glenn Research Center, Cleveland, Ohio

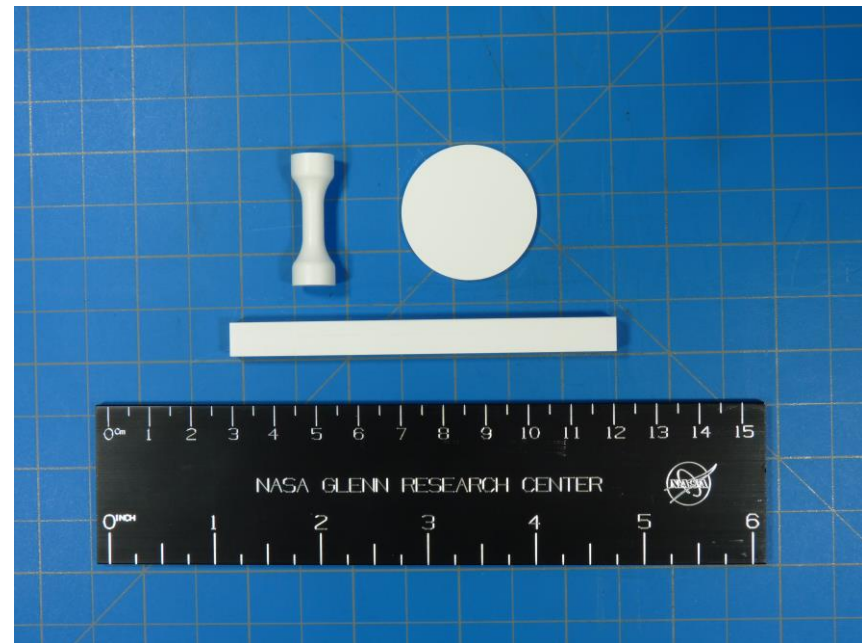
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Background

- Focus of this work are commercially available machinable ceramics for electric propulsion components.
 - Specifically interested in hot pressed boron nitride.
- Electric propulsion applications may subject ceramics to harsh environments including:
 - Plasma erosion, high temperature, low temperature, vacuum, and back-sputtered deposition.
 - Components may need to provide electrical isolation, thermal isolation, or some limited structural support.
- This work investigates material properties of various commercially available ceramic materials with a focus on lot-to-lot variation.





Materials of Interest

- Several commercial hexagonal boron nitride grades are being considered in this study.
- Grades considered were selected from geometric considerations for typical components.
- Previous study focused on “Lot 1”, this work investigates differences for “Lot 2” compared against “Lot 1”.

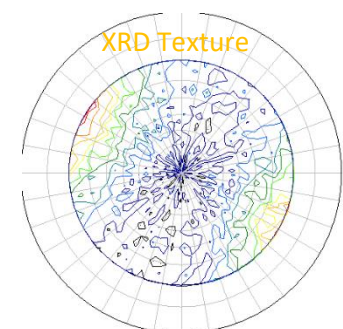
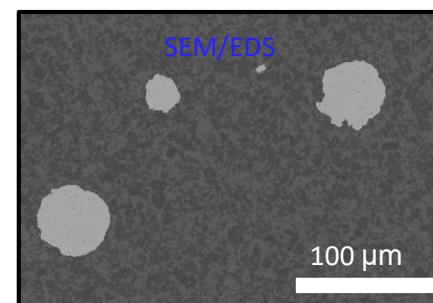
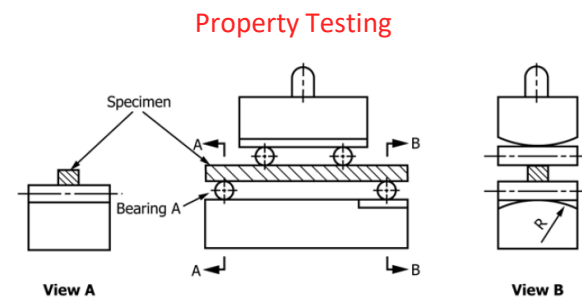
Grade*	Vendor*	Description	Relative Cost**	Lot 1	Lot 2
HP	Saint-Gobain	BN Ca(BO ₂) ₂ Binder	1.0	HP6073, HP6035	T3044
M26	Saint-Gobain	BN/SiO ₂ Composite	1.1	M266072	M266037, M268032
M	Saint-Gobain	BN/SiO ₂ Composite	1.0	M5118	M6011
BN-XX	Kennametal	BN/SiO ₂ /ZrO ₂ Composite	1.0	N/A	N/A
Hi-M	Tokuyama/ Precision Ceramics	AlN/BN Composite	4.6	N/A	N/A

* Trade names and vendors are used for identification purposes only.

** Cost normalized to HP grade for comparable lot sizes.

Factors of Interest

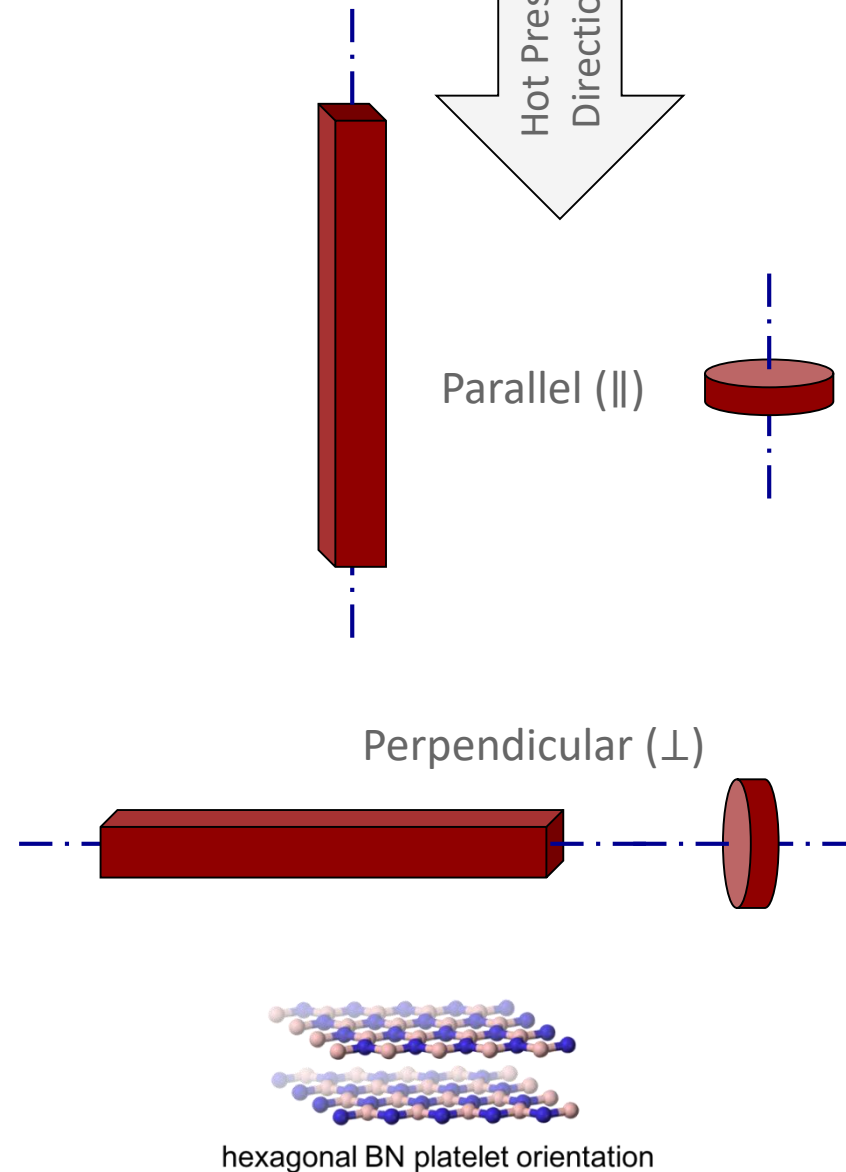
- **Primary** factors of interest:
 - Dielectric properties, thermal properties, mechanical properties, moisture sensitivity, secondary electron emission yield, thermal stability, and erosion resistance in a plasma environment.
- **Secondary** factors of interest:
 - Microstructure, crystal structure, details of processing, and mass spectroscopy.
- **Additional** factors to consider:
 - Hot press anisotropy, lot-to-lot property variability, billet uniformity/property variability, storage/handling concerns, and machining concerns.
- **Beyond** materials characterization work:
 - component fabrication and testing.



General Properties Overview



- Building dataset to contrast between different grades and against corporate literature.
 - Estimating measurement uncertainty from instrument uncertainty and sample size statistics.
 - Collecting data over a range of temperatures from 25 to 900°C whenever possible.
 - Following ASTM standards whenever possible.
- Collecting data on samples with primary measurement direction “Parallel \parallel ” or “Perpendicular \perp ” to the hot press direction.



General Properties Overview (cont.)



Property trends in BN/SiO₂ content

Property	Method	HP	M26	BN-XX	M
		/ ⊥	/ ⊥	/ ⊥	/ ⊥
XRD BN Phase (wt%)	Rietveld-refinement	98	70	56	45
Porosity (%)	ASTM C830	<14	<4.7	<2.4	<3.0
CTE (μm/m-K)	Dilatometry	3.1 / 0.4	2.9 / 0.5	N/A	0.5 / 0.6
Dielectric Constant	Impedance Spectroscopy	4.7 / 4.6	4.6 / 4.7	4.1	4.0 / 4.2
Thermal Conductivity (W/m-K)	ASTM E1461	33 / 31	22 / 28	6	9 / 12
Elastic Modulus (GPa)	ASTM C1259	80 / 79	55 / 47	N/A	16 / 61

* All data collected at NASA GRC or California Institute of Technology

General Properties Overview (cont.)



Property trends in BN/SiO₂ content

Property	Method	HP / ⊥	M26 / ⊥	BN-XX / ⊥	M / ⊥
XRD BN Phase (wt%)	Rietveld-refinement	98	70	56	45
Porosity (%)	ASTM C830	<14	<4.7	<2.4	<3.0
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Dielectric Constant	Impedance Spectroscopy	4.7 / 4.6	4.6 / 4.7	4.1	4.0 / 4.2
Thermal Conductivity (W/m-K)	ASTM E1461	33 / 31	22 / 28	6	9 / 12
Elastic Modulus (GPa)	ASTM C1259	80 / 79	55 / 47	N/A	16 / 61

* All data collected at NASA GRC or California Institute of Technology



General Properties Overview (cont.)

Property	Density			X M / ⊥	
	Grade	Geometric Density (g/cm ³)	Archimedes Density (g/cm ³) Porosity (%)		
Lot 1					
XRD BN Phase (wt%)	HP	1.95-1.99 [0.01]	1.95-1.98 [0.01]	12.7-14.4 [1]	45
Porosity (%)	M26	2.10-2.13 [0.01]	2.10-2.12 [0.01]	0.7-4.6 [1]	<3.0
CTE (μm/m-K)	M	2.12-2.13 [0.01]	2.12-2.13 [0.01]	0.3-3.0 [1]	0.5 / 0.6
Lot 2					
Dielectric Constant	HP	1.96-2.07 [0.01]	1.95-2.07 [0.01]	9.6-13.8 [1]	4.0 / 4.2
Thermal Conductivity (W/m-K)	M26	2.03-2.10 [0.01]	2.03-2.07 [0.01]	6.7-9.2 [1]	9 / 12
Elastic Modulus (GPa)	M	2.08-2.14 [0.01]	2.09-2.13 [0.01]	0.9-4.5 [1]	16 / 61

More variability observed in Lot 2

* All data

General Properties Overview (cont.)

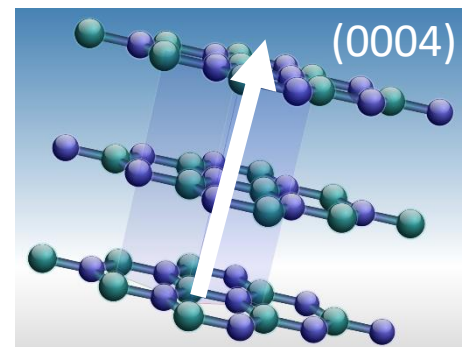


Property		Thermal		
		Lot 1		
Property	Measurement	Grade	Emissivity 630°C	CTE 400-800°C (10 ⁻⁶ /K)
XRD BN Phase (wt%)	Rietveld	HP	0.82 [0.01]	3.1 [0.5]
		HP ⊥	0.81 [0.01]	0.4 [0.4]
Porosity (%)	ASTM	M26	0.80 [0.01]	2.9 [0.1]
		M26 ⊥	0.75 [0.01]	0.5 [0.2]
CTE (μm/m-K)	Dilatometer	M	0.76 [0.01]	0.5 [0.1]
		M ⊥	0.71 [0.01]	0.6 [0.1]
Dielectric Constant	Impedance			
Thermal Conductivity (W/m-K)	ASTM			
Elastic Modulus (GPa)	ASTM			
		Lot 2		
		Grade	Emissivity 630°C	CTE 400-800°C (10 ⁻⁶ /K)
		HP	0.85 [0.01]	3.4 [0.5]
		HP ⊥	0.81 [0.01]	0.5 [0.4]
		M26	0.79 [0.01]	2.8 [0.1]
		M26 ⊥	0.80 [0.01]	0.6 [0.2]
		M	0.82 [0.01]	1.8 [0.2]
		M ⊥	0.83 [0.01]	0.8 [0.1]

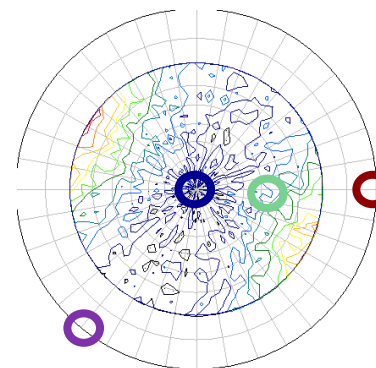
* All data collected at 25°C

Hot Press Anisotropy

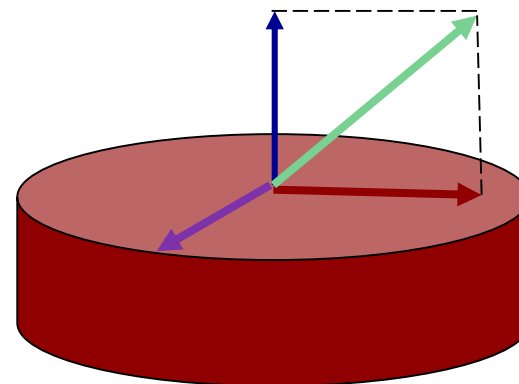
- Hot pressed BN platelets tend to align during processing.
- Property anisotropy strongest in CTE, Thermal conductivity, and Flexural strength data.
- Characterize crystallographic texture with XRD pole figures.
 - Can also be used to identify unknown hot press direction.



Crystallographic Direction



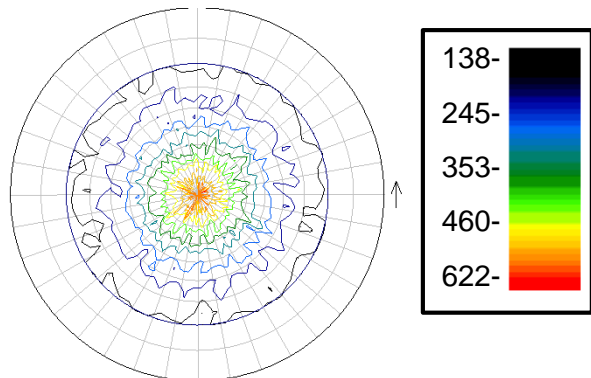
Stereographic Projection



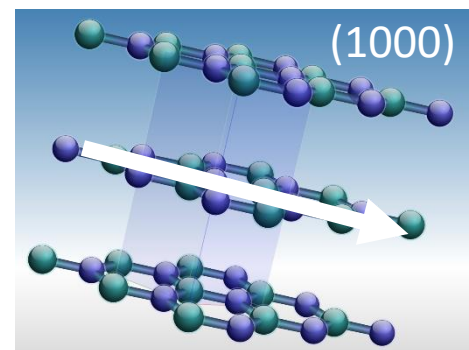
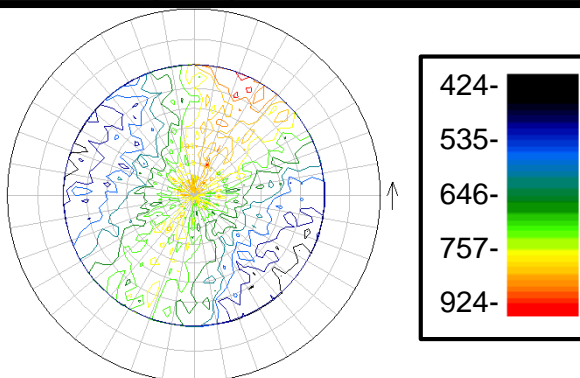
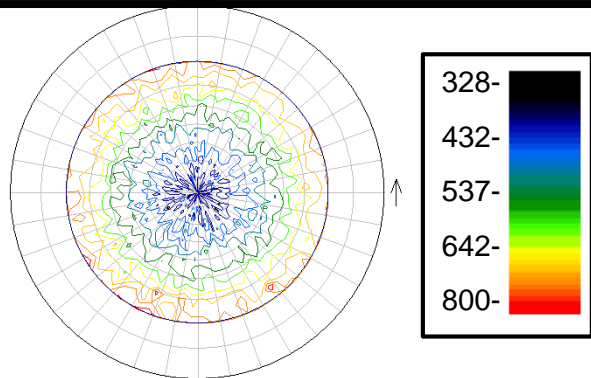
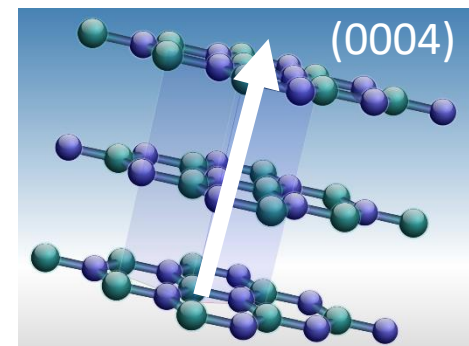
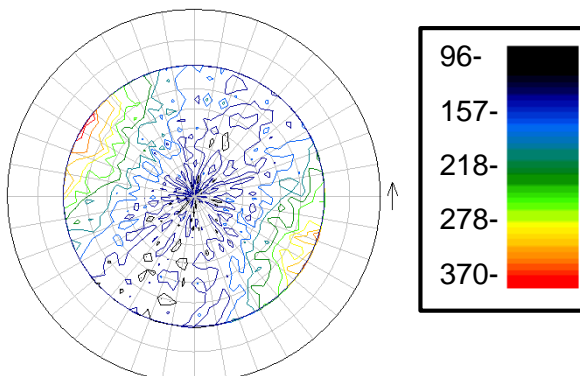
Sample

Hot Press Anisotropy (cont.)

HP || Hot Press



HP ⊥ Hot Press

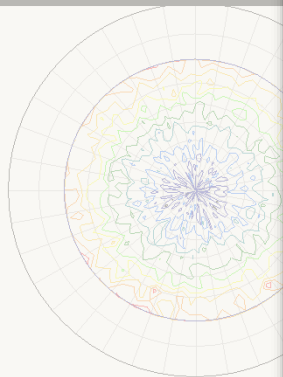
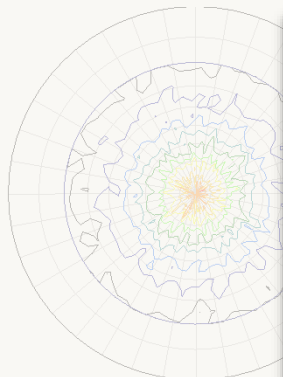


- HP, M26, and M grades evaluated with XRD pole figures.
- HP & M26 (98 & 70 wt% BN) show similar level of texturing, M (45 wt% BN) is less textured based on maximum intensity.
- Texture is consistent with hot press orientation in all samples tested.
 - Some samples have up to 10° mis-alignment between axial direction and maximum (0004) direction.

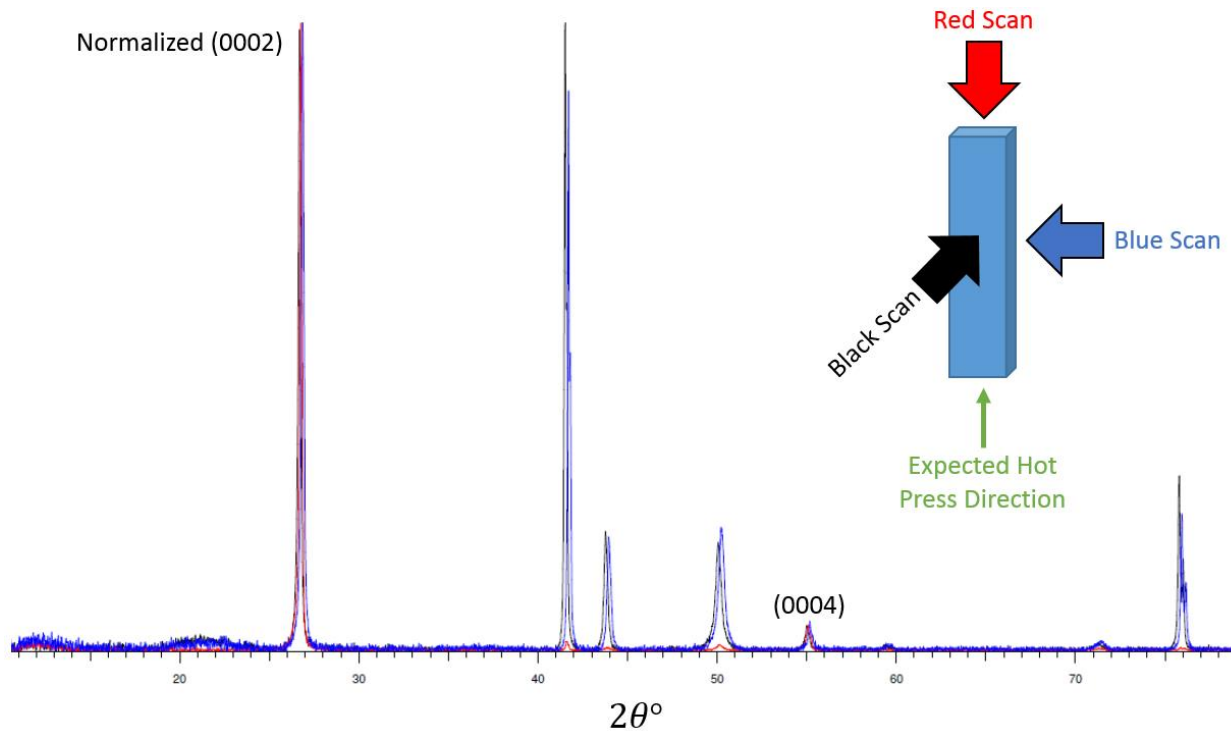
Hot Press Anisotropy (cont.)

HP || Hot Press

HP ⊥ Hot Press



Anisotropy



Lot 2 was confirmed to have similar hot press anisotropy

- HP, M26, a
- HP & M26 textured ba
- Texture is consistent with hot press orientation in all samples tested.

– Some samples have up to 10° mis-alignment between axial direction and maximum (0004) direction.

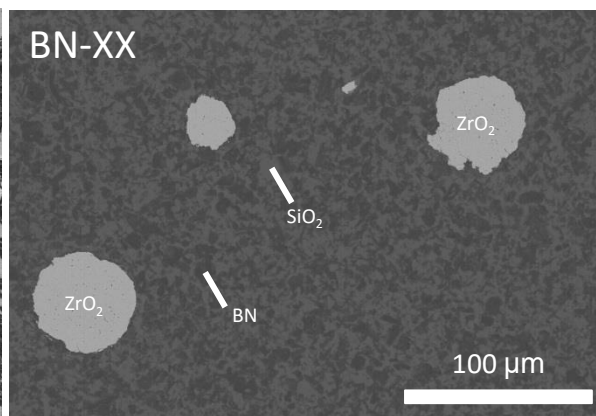
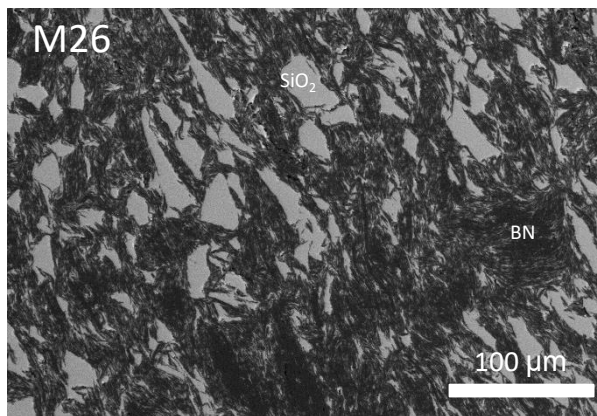
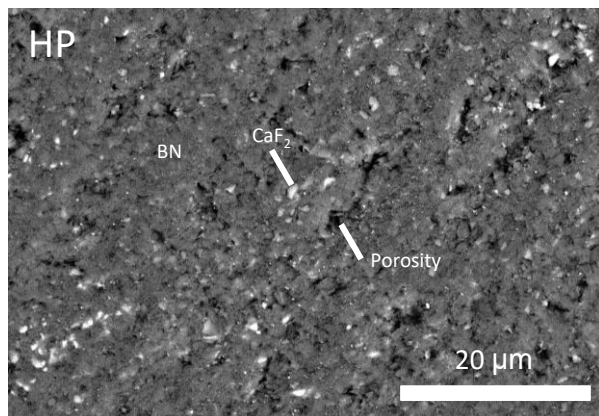
Microstructure Overview

- SEM microstructure is not clearly textured by hot press direction.
- Porosity is apparent in HP grade, less in other grades.
- M26, BN-XX, and M have similar BN/SiO₂ structure.
- XRD phase analysis matches with micrograph area analysis.

Powder XRD Rietveld Refinement

Grade	BN (wt%)	CaF ₂ (wt%)	ZrO ₂ (wt%)	AlN (wt%)	Amorp. (wt%)*
HP	98	2	0	0	0
M26	68	0	0	0	32
BN-XX	56	0	1	0	43
M	41	0	0	0	59
Hi-M	27	0	0	72	0

*Amorphous content is likely SiO₂, confirmed with EDS.

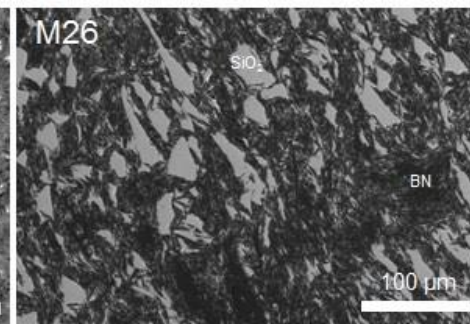
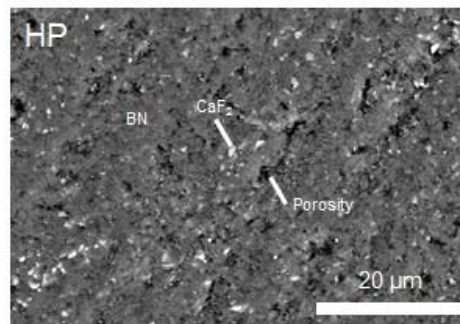


Microstructure Overview

Microstructure

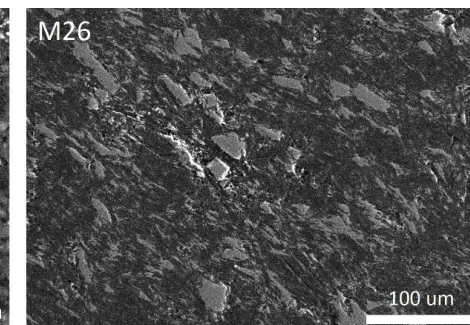
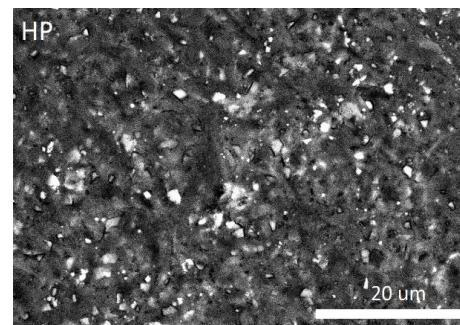
Lot 1

Grade	BN (wt%)	CaF ₂ (wt%)	ZrO ₂ (wt%)	AlN (wt%)	Amorp. Bal. (wt%)*
HP	98	2	0	0	0
M26	68	0	0	0	32
M	41	0	0	0	59



Lot 2

Grade	BN (wt%)	CaF ₂ (wt%)	ZrO ₂ (wt%)	AlN (wt%)	Amorp. Bal. (wt%)*
HP	98	2	0	0	0
M26	74	0	0	0	25
M	38	0	0	0	62



Lot 2 similar within expected capability to determine amorphous content

Lot 2 microstructure qualitatively and semi-quantitatively similar

Moisture Absorption

- Samples were subjected to one of three moisture levels for >20 days while mass change was tracked.
 - Drying Oven, 100C, <5% rel. humidity.
 - Environmental Chamber, 50C, 90% rel. humidity.
 - Submerged Water Bath, 25C, 100% rel. humidity.
 - Each hot press orientation was investigated on high aspect ratio samples.

Drying Oven
100C, <5% rel. humidity, 50 days



Submerged in Water
25C, 100% rel. humidity, 90 days





Moisture Absorption (cont.)

- Mass change tracks with open pore porosity (high, medium, low).
- HP hot press orientation has influence on the transfer of moisture (high, low).
- HP samples produced a $\text{CaB}_6\text{O}_9(\text{OH})_2(\text{H}_2\text{O})_3$ salt on the surface of the submerged samples.

Sample	Porosity (%)	Dry Oven, 100C Mass Loss (%)	90% Chamber, 50C Mass Gain (%)	Submerged, 25C Mass Gain (%)
HP	<14	1.1 ± 0.5	0.97 ± 0.07	4.6 ± 0.3
HP ⊥	<14	0.12 ± 0.01	0.33 ± 0.05	3.7 ± 0.5
M26	<4.7	0.025 ± 0.003	0.020 ± 0.005	2.7 ± 0.3
M26 ⊥	<4.7	0.035 ± 0.004	0.019 ± 0.008	3.2 ± 0.8
M	<3.0	0.026 ± 0.005	0.018 ± 0.005	1.8 ± 0.1
M ⊥	<3.0	0.036 ± 0.003	0.005 ± 0.003	1.7 ± 0.1



Moisture Absorption (cont.)

- Mass change tracks with open pore porosity (**high**, **medium**, **low**).
- HP hot press orientation has influence on the transfer of moisture (high, low).
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M	<3.0	0.026 ± 0.005	0.018 ± 0.005	1.8 ± 0.1
M ⊥	<3.0	0.036 ± 0.003	0.005 ± 0.003	1.7 ± 0.1

Moisture Absorption (cont.)

- Mas
- HP
- HP s

Moisture Absorption

Lot 1

Grade	Dry Oven Mass Change (%)	Environment Chamber Mass Change (%)
HP	-1.1 [0.5]	0.97 [0.07]
HP ⊥	-0.12 [0.01]	0.33 [0.05]
M26	-0.025 [0.003]	0.020 [0.005]
M26 ⊥	-0.035 [0.004]	0.019 [0.008]
M	-0.026 [0.005]	0.018 [0.005]
M ⊥	-0.036 [0.003]	0.005 [0.003]

Lot 2 dry oven results are similar to Lot 1.

Lot 2 environmental chamber results are inconsistent and have standard deviations as large as 100% of average.

Lot 2

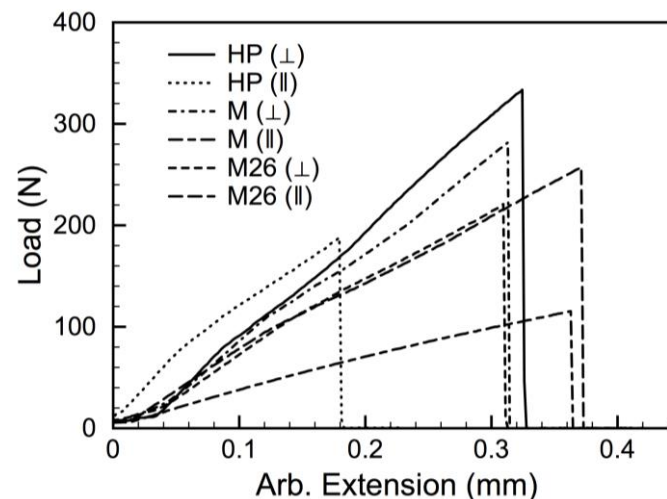
Grade	Dry Oven Mass Change (%)	Environment Chamber Mass Change (%)
HP	-0.697 [0.596]	-0.241 [0.245]
HP ⊥	-0.208 [0.064]	0.056 [0.012]
M26	-0.043 [0.005]	0.017 [0.005]
M26 ⊥	-0.043 [0.011]	0.099 [0.081]
M	-0.012 [0.006]	0.046 [0.024]
M ⊥	-0.013 [0.004]	0.047 [0.011]

Lot 2 environmental chamber settings were different from lot 1.

Flexural Testing

- 4-point bend testing performed on HP, M, and M26.
 - 26+ room temperature samples and 10 high temperature samples per configuration.
 - \parallel and \perp hot press orientations, as-machined, dry oven, and humidity chamber samples.
- All grades exhibited brittle failure at room temperature (25°C).
- HP exhibited significant deflection at 600°C .
 - Possibly CaF_2 or $\text{CaB}_6\text{O}_9(\text{OH})_2(\text{H}_2\text{O})_3$ related mechanism.
- HP \parallel suffered significant decrease in strength at 600°C .

Representative load extension curves



HP \parallel
 25°C



HP \parallel
 600°C



Flexural Testing (cont.)

- Weibull modulus of all grades ranged from 7 to 22.
 - M and M26 have similar Weibull modulus at 600°C as room temp.
- M \parallel strength is significantly below literature values (103 MPa Literature), consistent at room temperature and 600°C.

Sample	Room Temperature			600°C		
	Average (MPa)	Std. Dev. (MPa)	Weibull Modulus	Average (MPa)	Std. Dev. (MPa)	Weibull Modulus
HP \parallel	39.7	2.3	19.3	9.8	4.7	-
HP \perp	70.5	3.6	22.3	70.1	9.7	-
M26 \parallel	55.6	7.3	8.6	66.3	6.7	10.7
M26 \perp	45.0	6.6	7.0	56.2	8.1	7.6
M \parallel	23.6	2.0	13.4	27.7	1.8	15.2
M \perp	59.1	5.9	11.2	71.4	8.7	8.6

Flexural Testing (cont.)

- Weibull
- M and
- M || stren
- MPa Lite
- 600°C.

Mechanical					
Lot 1			Lot 2		
Grade	Flexural Strength 25°C (MPa)	Dynamic Modulus (GPa)*	Grade	Flexural Strength 25°C (MPa)	Dynamic Modulus (GPa)
HP	39.7 [2.3]	80 [3]	HP	22.8 [4.0]	36.9 [1.0]
HP ⊥	70.5 [3.6]	79 [3]	HP ⊥	57.6 [3.7]	75.1 [1.0]
M26	55.6 [7.3]	55 [11]	M26	19.9 [0.9]	83.9 [4.1]
M26 ⊥	45.0 [6.6]	47 [7]	M26 ⊥	47.9 [1.7]	49.8 [6.2]
M	23.6 [2.0]	16 [1]	M	39.1 [7.1]	58.3 [3.3]
M ⊥	59.1 [5.9]	61 [3]	M ⊥	65.0 [6.1]	26.5 [3.4]

Lot 2 differences are significant for strength and modulus of all grades.

Sample						
HP						
HP ⊥						
M26	55.6	7.3	8.6	66.3	6.7	10.7
M26 ⊥	45.0	6.6	7.0	56.2	8.1	7.6
M	23.6	2.0	13.4	27.7	1.8	15.2
M ⊥	59.1	5.9	11.2	71.4	8.7	8.6

Moisture Sensitivity

- Samples from moisture absorption study were tested for flexural strength and elastic modulus after soak.
- HP \parallel , HP \perp , and M \parallel , all have significant changes in strength and elastic modulus properties with moisture exposure ($P < 0.05$).

	<5% Rel. Humidity	~60% Rel. Humidity	90% Rel. Humidity	
Sample	Dry Oven Strength (MPa)	As-machined Strength (MPa)	90% Chamber Strength (MPa)	P-Value [Oven>Chamber]
HP \parallel	52.1	42.5	27.5	0.000005
HP \perp	80.1	76.1	69.7	0.005
M26 \parallel	59.9	61.8	57.9	0.3
M26 \perp	43.2	49.6	39.7	0.2
M \parallel	23.9	24.7	22.3	0.01
M \perp	60.1	62.4	59.2	0.3

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HP \parallel	52.1	42.5	27.5	0.000005
HP \perp	80.1	76.1	69.7	0.005
M26 \parallel	59.9	61.8	57.9	0.3
M26 \perp	43.2	49.6	39.7	0.2
M \parallel	23.9	24.7	22.3	0.01
M \perp	60.1	62.4	59.2	0.3



Moisture Sensitivity

Lot 1

Grade	Dry Oven Strength (MPa)	As-Machined Strength (MPa)	Environment Chamber Strength (MPa)	P-Value [Oven>Chamber]
HP	52.1 [5]	42.5 [3]	27.5 [2]	<0.005
HP ⊥	80.1 [3]	76.1 [4]	69.7 [6]	0.005
M26	59.9 [9]	61.8 [10]	57.9 [7]	0.3
M26 ⊥	43.2 [8]	49.6 [8]	39.7 [8]	0.2
M	23.9 [1]	24.7 [1]	22.3 [1]	0.01
M ⊥	60.1 [2]	62.4 [4]	59.2 [6]	0.3

Lot 2

Grade	Dry Oven Strength (MPa)	As-Machined Strength (MPa)	Environment Chamber Strength (MPa)	P-Value [Oven>Chamber]
HP	32.2 [5]	22.8 [4]	18.8 [3]	<0.005
HP ⊥	67.3 [8]	57.6 [4]	62.9 [5]	0.07
M26	22.0 [1]	19.9 [1]	20.6 [1]	0.02
M26 ⊥	53.6 [4]	47.9 [2]	47.0 [1]	<0.005
M	35.9 [6]	39.1 [7]	36.8 [7]	0.3
M ⊥	37.2 [5]	65.0 [6]	60.8 [10]	<0.005

Lot 2 is more moisture sensitive.



Summary

- So far only two lots have been characterized, so the following statements should be interpreted appropriately.
- Properties with significant lot-to-lot variation:
 - Flexural strength, elastic modulus, moisture sensitivity
- Properties with minimal lot-to-lot variation:
 - Density, moisture absorption
- Properties with no lot-to-lot variation:
 - CTE, emissivity, microstructure, surface roughness, trace contaminants, anisotropy, composition
- Properties not yet characterized on multiple lots:
 - Slow crack growth, fracture toughness, compression strength, coefficient of sliding friction, thermal conductivity, electrical properties, specific heat
- Lot testing is strongly recommended for critical applications.



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